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## what is claimed is:

- A method for controlling an electroplating process, the method
  comprising:
  - (a) obtaining a sample of electrolyte from the electroplating process;
  - (b) analyzing the sample of electrolyte by mass spectrometry to obtain a mass spectral result;
  - (c) comparing the mass spectral result to a plurality of known mass spectral results; and
  - (d) adjusting conditions of the electroplating process in response to the comparison.
  - The method of claim 1, wherein the sample of electrolyte is obtained directly from a plating cell of the electroplating process.
  - The method of claim 1, wherein the sample of electrolyte is obtained directly from a separate sampling vessel of the electroplating process.
  - 4. The method of claim 1, wherein the sample of electrolyte is obtained from a central chemistry vessel of the electroplating process.
- The method of claim 1, wherein the sample of electrolyte is analyzed
  using atmospheric pressure ionization mass spectrometry.
  - 6. The method of claim 1, wherein the sample of electrolyte is analyzed using at least one mass spectrometry technique selected from the group consisting of API-MS, Quadrupole MS, Ion Trap MS, Magnetic Sector MS, and Time-of-Flight MS.
  - The method of claim 1, wherein the plurality of known mass spectral results is stored in a memory device.

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- 8. The method of claim 7, further comprising determining whether the mass spectral result falls within a specified tolerance of a target result that is one of the plurality of known mass spectral results.
- 5 9. The method of claim 1, wherein the plurality of known spectral results are provided for a plurality of compositions comprising at least one of organic plating additives and breakdown products of said additives.
- The method of claim 1, wherein adjusting conditions of the electroplating
  process comprises adjusting electroplating apparatus hardware.
  - 11. The method of claim 10, wherein adjusting electroplating apparatus hardware comprises adjusting an electrolyte composition.
- 15 12. The method of claim 10, wherein adjusting electroplating apparatus hardware comprises adjusting an electrical current flow.
  - The method of claim 10, wherein adjusting electroplating apparatus hardware comprises adjusting a field shaping apparatus.
  - $14. \hspace{0.5cm} \hbox{The method of claim $10$, wherein adjusting electroplating apparatus hardware comprises adjusting a voltage level.}$
- 15. The method of claim 10, wherein adjusting electroplating apparatus25 hardware comprises adjusting a wafer handling apparatus.
  - 16. The method of claim 10, wherein adjusting electroplating apparatus hardware comprises adjusting a relative orientation of an electrode with a counter electrode.
  - The method of claim 1, wherein, the mass spectral result is obtained for each cassette of wafers processed.
- 18. The method of claim 1, wherein, the mass spectral result is obtained for 35 each wafer processed.

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- 19. The method of claim 1, wherein, the mass spectral result is obtained multiple times for each wafer processed.
- 20. An apparatus for controlling an electroplating process, the apparatus comprising:
  - (a) a mass spectrometer equipped with an electrolyte sampling device and an ionization source configured to deliver a sample of ionized electrolyte to the mass spectrometer; and
  - (b) an associated logic for controlling the electroplating process based on a result obtained from the mass spectrometer upon analysis of the sample of ionized electrolyte.
  - The apparatus of claim 20, wherein the electrolyte sampling device collects electrolyte directly from a plating bath of the electroplating process.
  - 22. The apparatus of claim 20, wherein the electrolyte sampling device collects electrolyte from a separate sampling vessel that receives electrolyte from a plating bath of the electroplating process.
  - 23. The apparatus of claim 20, wherein the electrolyte sampling device collects electrolyte from a separate sampling vessel that receives electrolyte from a plating bath of the electroplating process.
- 24. The method of claim 20, wherein the electrolyte sampling device collectselectrolyte from a central chemistry vessel of the electroplating process.
  - 25. The apparatus of claim 20, wherein the associated logic compares the result to a plurality of known mass spectral results in order to determine commands for controlling the electroplating process.
  - 26. The apparatus of claim 25, wherein the plurality of known mass spectral results is stored in a memory device.
- A method for controlling a wafer wet process in integrated circuit
  fabrication, the method comprising:

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- (a) obtaining a sample of processing solution from the wafer wet process:
- (b) analyzing the sample of processing solution by mass spectrometry to obtain a result:
- (c) comparing the result to a plurality of known mass spectral results; and  $% \left( 1\right) =\left( 1\right) \left( 1\right$
- (d) adjusting conditions of the wafer wet process in response to the comparison.
- The method of claim 27, wherein the sample of processing solution is analyzed using atmospheric pressure ionization mass spectrometry.
  - 29. The method of claim 27, wherein the plurality of known mass spectral results is stored in a memory device.
  - 30. The method of claim 29, further comprising determining whether the result falls within a specified tolerance of a target result that is one of the plurality of known mass spectral results.
  - 31. An apparatus for controlling a wafer wet process in integrated circuit fabrication, the apparatus comprising:
    - (a) a mass spectrometer equipped with a sampling device and an ionization source configured to deliver a sample of ionized processing solution from the wet process to the mass spectrometer; and
    - (b) an associated logic for controlling the wafer wet process based on a result obtained from the mass spectrometer upon analysis of the sample of ionized processing solution.
- 32. The apparatus of claim 31, wherein the associated logic compares the result to a plurality of known mass spectral results in order to determine commands for controlling the wafer wet process.
  - 33. The apparatus of claim 32, wherein the plurality of known mass spectral results is stored in a memory device.

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- 34. A computer program product comprising a machine readable medium on which is provided instructions for controlling an electroplating process, the instructions comprising program code for adjusting conditions of the electroplating process in response to a mass spectral analysis of an electrolyte sample from said electroplating process.
- 35. The computer program product of claim 34, wherein the mass spectral analysis includes a comparison of mass spectral data for said electrolyte sample to a plurality of known mass spectral data.

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